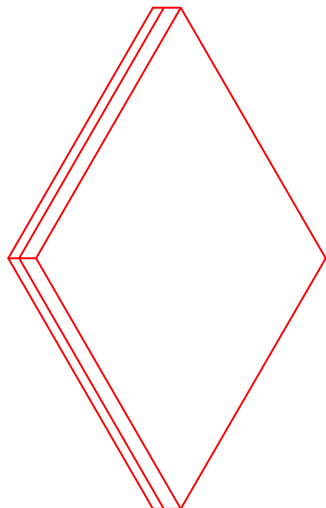


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REV:	DESCRIPTION	DATE	CHECKED	DESIGNED BY
00	INITIAL RELEASE PER DCN C06106	05/06/99	E.B.	M.C.N.



7. REFERENCE SPECIFICATIONS:  
 A. AMM SPEC #2001-2294: PACKING OPERATION PROCEDURE.  
 B. AMM SPEC #2001-0519-2002: MARKING.
6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BUMPS IS 49.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 7 X 7.
2. THE BASIC SOLDER BUMP GRID PITCH IS 0.90mm.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS	ANGULARS ±1°	PRODUCTION		DATE	DATE	TITLE	AMCOR Industrial Co., Ltd. Singapore, Singapore AMCOR Electronics Inc. Chandler, Arizona, USA	
		APPROVALS	DATE					
XX ±0.10		DESIGN M. HOBBS	04/14/99	04/29/99	04/14/99	PACKAGE OUTLINE - CTBGA 49, 6.00mm X 6.00mm, 2 LAYER, 0.90mm PITCH, LAMINATE SUBSTRATE, AAP		
XX.XX ±0.05		CHECKED J. MARCICH	04/14/99	04/29/99	04/14/99			
X.XXX ±0.03		NOTES H. BUDZIALOWSKI	04/14/99	04/29/99	04/14/99			
		PREPARED N/A						
		DO NOT SCALE DRAWING						